02-22-1999

Docket No. JCLA4080

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.S. Department of Commerce
Patent and Trademark Office

# PATENTS ONLY

To the Honorable Assistant Commissioner for Patents: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Chih-Hung Cheng

2. Name/address of receiving Party(ies):

United Semiconductor Corp.

No 3, Li-Hsin Rd. II, Science-Based
Industrial Park, Hsinchu,
Taiwan, R.O.C.

Add'l names of receiving parties Attached? ☐ Yes ☒ No

3. Nature of conveyance: ☒ Assignment
☐ Merger ☐ Security Agreement ☐Other
☐ Change of Name ☐ Reassignment

4. Date(s) of execution: January 19, 1999;

5. Application number(s) or patent number(s):

**If this documents is being filed together with a new application, the execution date of the application is January 19, 1999.**

A. Patent Application No. (s)

B. Patent No. ( s)

Additional numbers attached ? ☐ Yes ☒ No

6. Name and address of party to whom correspondence concerning document should be mailed:

J.C. Patents, Inc.
1340 Reynolds Ave., Suite 114
Irvine, CA 92614
(949) 660-0761

7. Total No. of applications and patents involved:

ONE(1)

8. Total fee (37 CFR §3.41): $40.00

☒ Enclosed

☐ Charge to Acct. No.

9. Total number of pages, including cover sheet, attachments and document 3.

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10. Statement and Signature:

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Jiawei Huang
Name of Person Signing

Jiawei Huang
Signature

2-8-99
Date

Registration No. 43, 330

# ASSIGNMENT

WHEREAS,

1. Chih-Hung Cheng

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **METHOD FOR FORMING SALICIDE LAYERS**

[ ] Filed: Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, United Semiconductor Corp.
of No. 3, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

# ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Chih-Hung Cheng
Signature:

January 19, 1999
Date:

Sole or First Joint Inventor: Chih-Hung Cheng